

## 100V, 108A N-Channel Power MOSFET

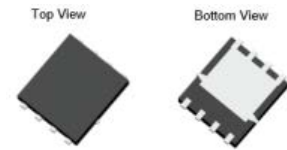
### DESCRIPTION :

- Ultra-Low  $R_{DS(ON)}$
- Low Gate Charge
- 100% UIS Tested, 100% Rg Tested
- Pb-Free Lead Plating
- RoHS compliant

$V_{DS}$	100V
$I_D @ V_{GS}=10V$	108A
$R_{DS(ON)_Typ. @ V_{GS}=10V}$	4.7m $\Omega$

### TYPICAL APPLICATIONS :

- Power Management
- Current Switch
- Motor Driving in Power Tool, E-Vehicle



PDFN5x6-8L

### MAXIMUM RATINGS (at $T_A = 25^\circ\text{C}$ , unless otherwise specified)

Characteristic	Condition	Symbol	Value	Unit
Drain-Source Voltage		$V_{DS}$	100	V
Gate-Source Voltage		$V_{GS}$	$\pm 20$	V
Continuous Drain Current	$T_c=25^\circ\text{C}$ $T_c=100^\circ\text{C}$	$I_D$	108 68	A
Pulsed Drain Current <sup>(1)</sup>		$I_{DM}$	388	A
Avalanche Current <sup>(2)</sup>		$I_{AS}$	47	A
Avalanche Energy <sup>(2)</sup>		$E_{AS}$	110	mJ
Power dissipation	$T_c=25^\circ\text{C}$ $T_c=100^\circ\text{C}$	$P_D$	130 52	W
Junction & Storage temperature Range		$T_J, T_{STG}$	-55~+150	$^\circ\text{C}$

Notes : 1. Repetitive Rating : Pulse Width Limited by Maximum Junction Temperature.

2. This single-pulse measurement was taken under the following condition [  $V_{DD}=50V, V_{GS}=10V, L=100\mu\text{H}$ ] while its value is limited by  $T_{J\_MAX}=150^\circ\text{C}$

### THERMAL CHARACTERISTICS

Characteristic	Condition	Symbol	Value	Unit
Thermal resistance,	Junction to Ambient Junction to Case	$R_{\theta JA}$ $R_{\theta JC}$	65 0.96	$^\circ\text{C/W}$

ELECTRICAL CHARACTERISTICS (at  $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise specified)

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage VGS = 0V, ID = 250uA	$V_{(BR)DSS}$	100			V
Zero Gate Voltage Drain Current VDS = 80 V, VGS = 0 V	$I_{DSS}$			1	uA
Gate-Source Leakage Current VGS = $\pm 20$ V, VDS = 0V	$I_{GSS}$			$\pm 100$	nA
Gate-Source threshold voltage VDS = VGS, ID = 250uA	$V_{GS(th)}$	1.2	1.9	2.5	V
Drain-Source On-State Resistance VGS = 10V, ID = 20A VGS = 4.5V, ID = 15A	$R_{DS(on)}$		4.7 5.9	5.9 7.7	m $\Omega$
Input capacitance f=1MHz, VDS=50 V, VGS=0 V	$C_{iss}$		2604		pF
Output capacitance f=1MHz, VDS=50 V, VGS=0 V	$C_{oss}$		567		pF
Reverse transfer capacitance f=1MHz, VDS=50 V, VGS=0 V	$C_{rss}$		9.6		pF
Gate Resistance f=1MHz, VDS=0 V, VGS=0 V	$R_g$		1.8		$\Omega$
Total Gate Charge VDS= 50V, ID= 20A, VGS= 10V VDS= 50V, ID= 20A, VGS= 4.5V	$Q_G$		42 28		nC
Gate to Source Charge VDS= 50V, ID= 20A, VGS= 0 to 10V	$Q_{GS}$		6.5		nC
Gate to Drain Charge VDS= 50V, ID= 20A, VGS= 0 to 10V	$Q_{GD}$		9.7		nC
Turn-on delay time VDS= 50V, VGS= 10V, $R_L=2.5\Omega$ , $R_{GEN}=6\Omega$	$t_{d(ON)}$		11.3		ns
Rise time VDS= 50V, VGS= 10V, $R_L=2.5\Omega$ , $R_{GEN}=6\Omega$	tr		17.6		ns
Turn-off delay time VDS= 50V, VGS= 10V, $R_L=2.5\Omega$ , $R_{GEN}=6\Omega$	$t_{d(OFF)}$		46		ns
Fall time VDS= 50V, VGS= 10V, $R_L=2.5\Omega$ , $R_{GEN}=6\Omega$	tf		36		ns

## Body Diode

ELECTRICAL CHARACTERISTICS (at  $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise specified)

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Diode Forward Voltage $V_{GS} = 0V, I_S = 1A$	$V_{SD}$		0.71	1.0	V
Maximum Continuous Body Diode Forward Current	$I_S$			130	A
Revers Recovery Time $I_F = 15A, dI_F/dt = 100A/us$	$T_{rr}$		49		ns
Revers Recovery Charge $I_F = 15A, dI_F/dt = 100A/us$	$Q_{rr}$		44		nC

Typical Performance Characteristics

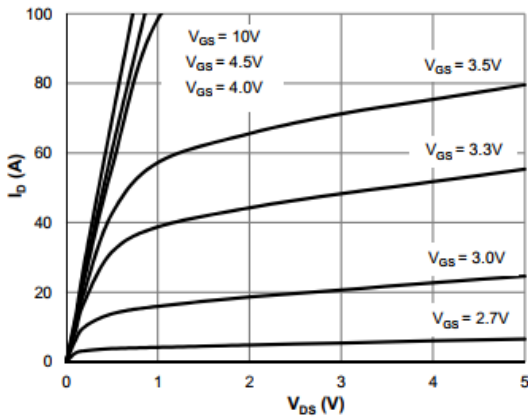


Figure 1. Saturation Characteristics

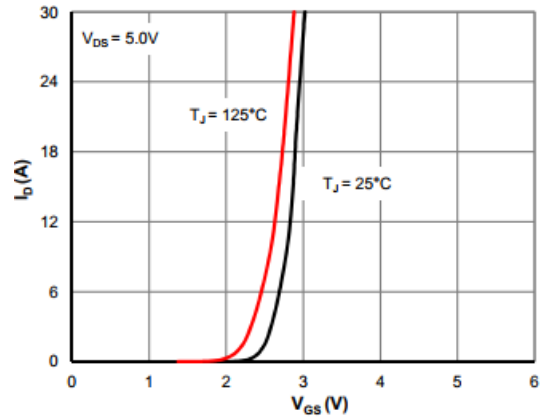


Figure 2. Transfer Characteristics

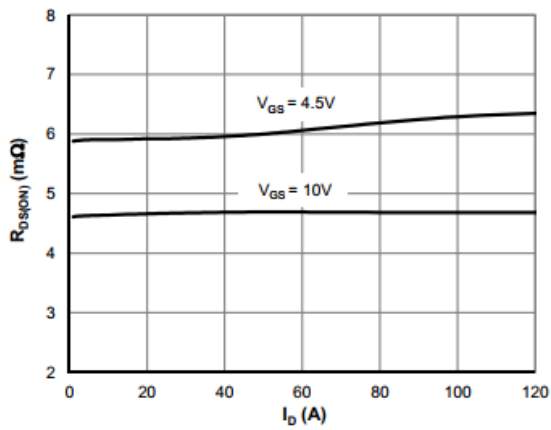


Figure 3. On-resistance vs. Drain Current

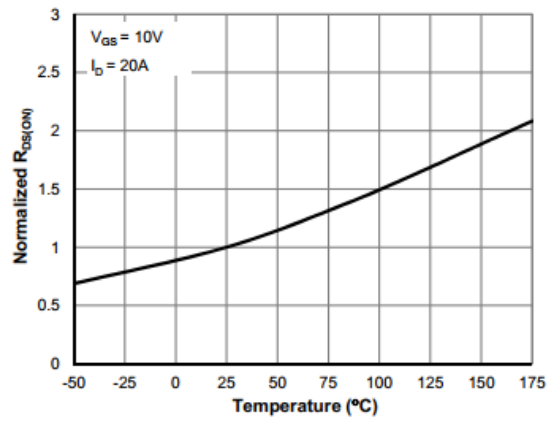


Figure 4.  $R_{DS(ON)}$  vs. Junction Temperature

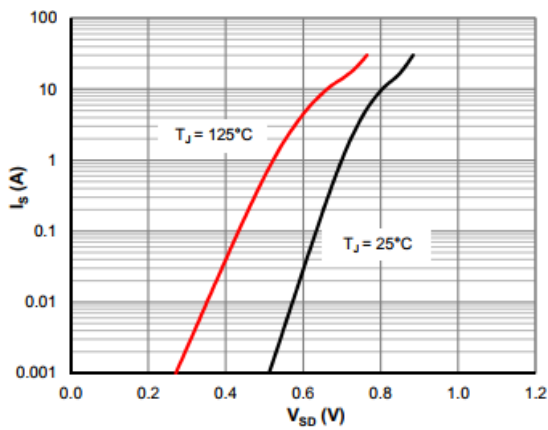


Figure 5. Body-Diode Characteristics

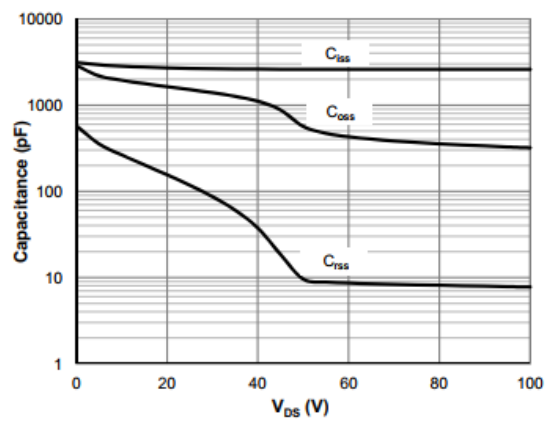


Figure 6. Capacitance Characteristics

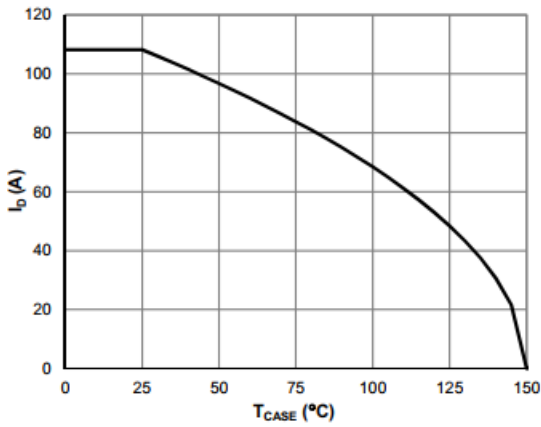


Figure 7. Current De-rating

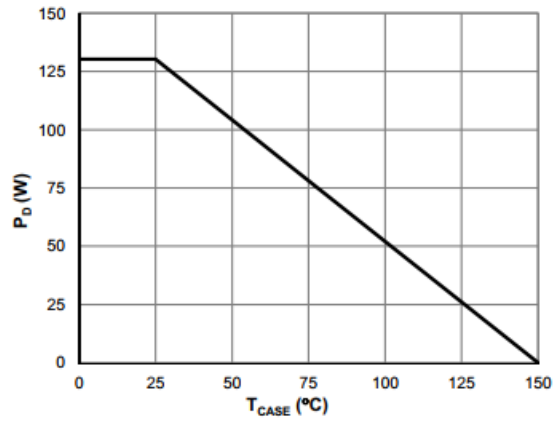


Figure 8. Power De-rating

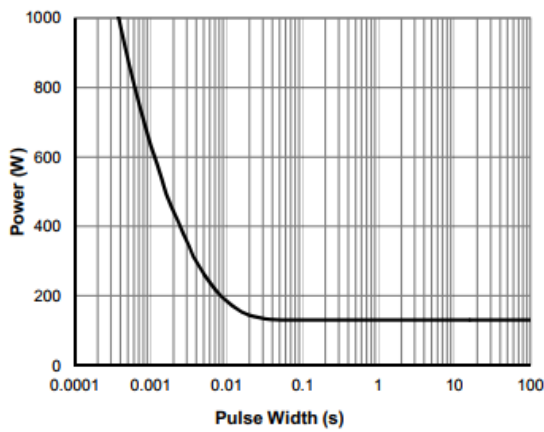


Figure 9. Single Pulse Power Rating, Junction-to-Case

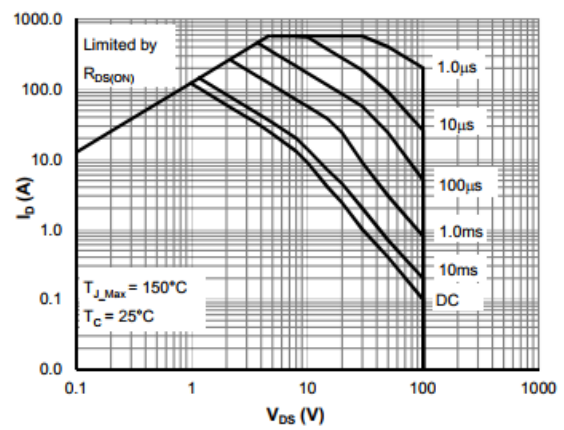


Figure 10. Maximum Safe Operating Area

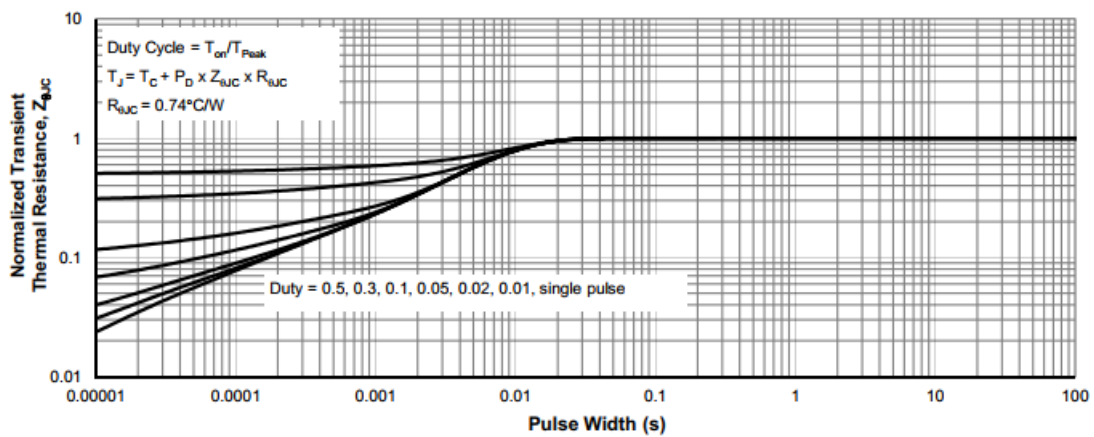
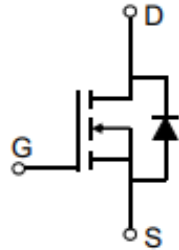
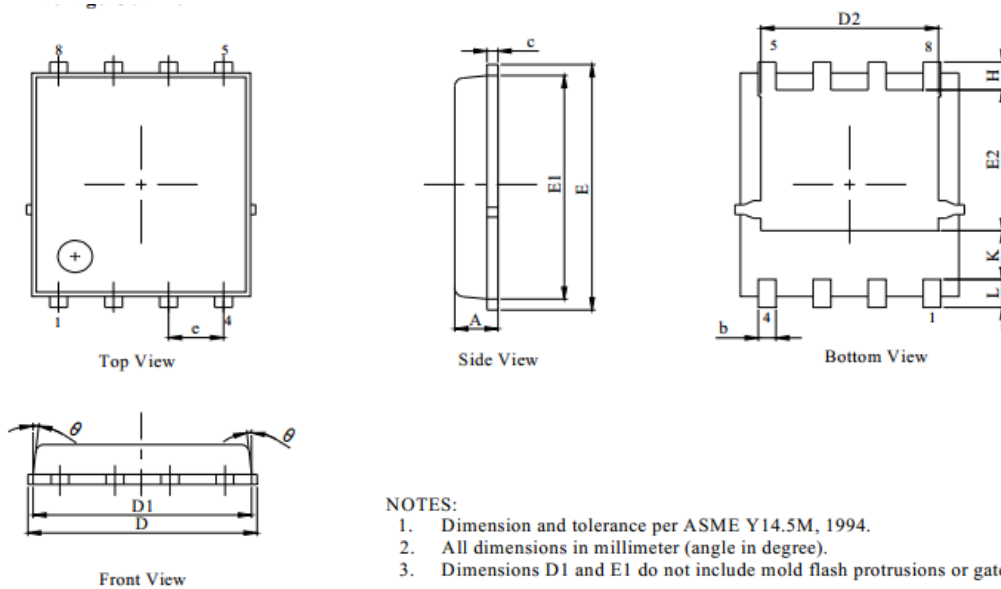


Figure 11. Normalized Maximum Transient Thermal Impedance

• Circuit diagram



• Package outlines :



NOTES:

1. Dimension and tolerance per ASME Y14.5M, 1994.
2. All dimensions in millimeter (angle in degree).
3. Dimensions D1 and E1 do not include mold flash protrusions or gate burrs.

DIM.	MILLIMETER		
	MIN.	NOM.	MAX.
A	0.90	1.00	1.10
b	0.31	0.41	0.51
c	0.20	0.25	0.30
D	5.00	5.20	5.40
D1	4.95	5.05	5.15
D2	4.00	4.10	4.20
E	6.05	6.15	6.25
E1	5.50	5.60	5.70
E2	3.42	3.53	3.63
e	1.27BSC		
H	0.60	0.70	0.80
L	0.50	0.70	0.80
K	1.23 REF		
θ	-	-	10°

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